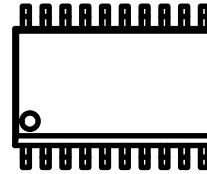


2.5 V/3.3 V Any Level
 Positive Input to
 -3.3 V/-5.5 V NECL
 Output Translator
 MC100EP91

Description



SOIC 20 WB

QFN 24

— μ

μ

Features

ORDERING INFORMATION

Device	Package	Shipping
	-	
	-	

DISCONTINUED

	-	
	-	

DISCONTINUED:

onsemi

MC100EP91

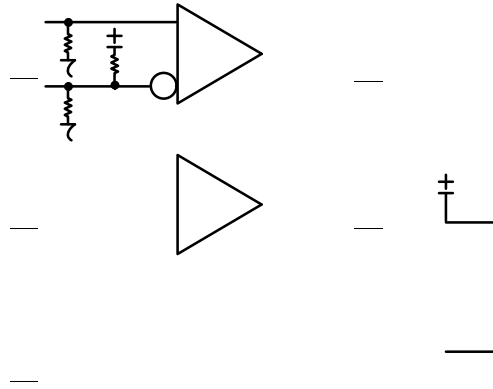


Figure 1. Logic Diagram

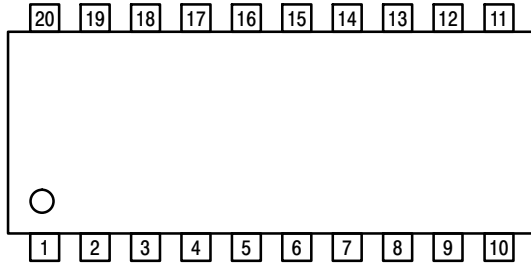


Figure 2. SOIC 20 Lead Pinout

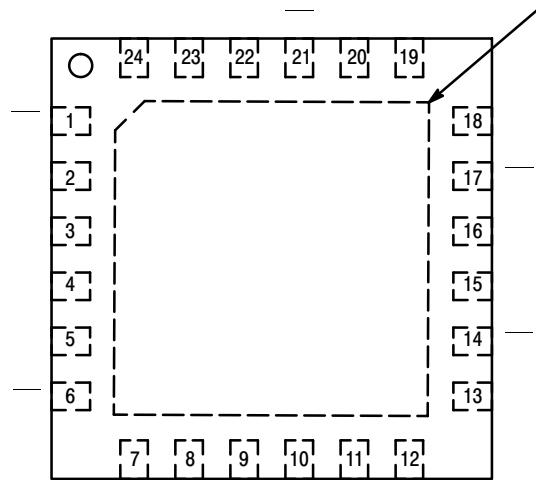


Figure 3. QFN 24 Lead Pinout

Table 2. ATTRIBUTES

Characteristics	Value
	Ω
	Ω
-	
-	
	-

MC100EP91

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
				-	
			-		
				-	
				-	
θ	-		-		
θ	-		-		
θ			-		

MC100EP91

Table 5. DC CHARACTERISTICS POSITIVE INPUT

Symbol	Characteristic	40 C	25 C	85 C	Unit
		Min			

MC100EP91

Table 7. AC CHARACTERISTICS

Symbol	Characteristic	40 C			25 C			85 C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	

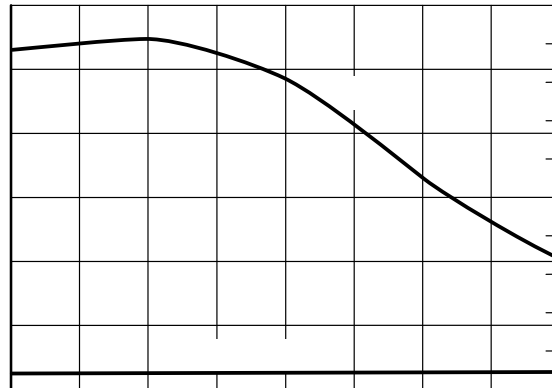


Figure 4. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)

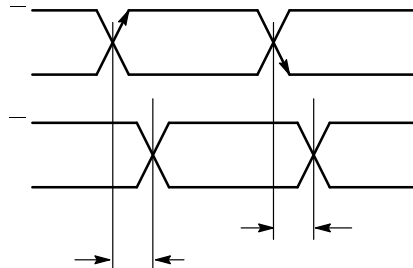


Figure 5. AC Reference Measurement

Application Information

MC100EP91

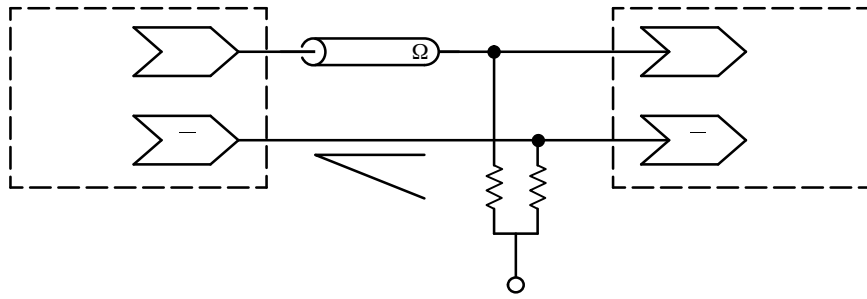
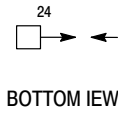
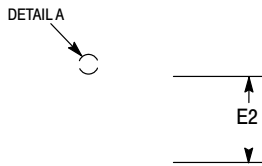
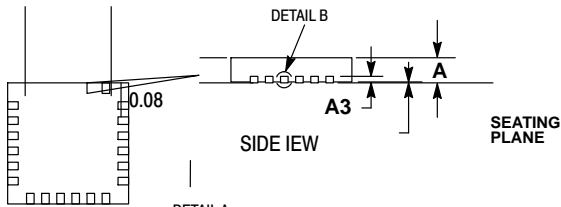
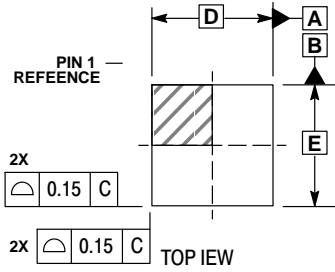


Figure 12. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) Termination of ECL Logic Devices)

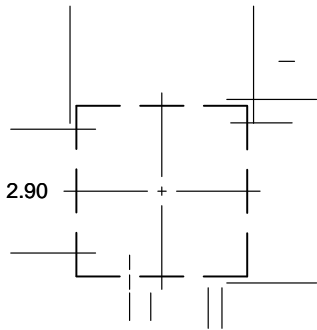
QFN24, 4x4, 0.5P
CASE 485L
ISSUE B

DATE 05 JUN 2012

f2.8360
 0.41 cm 0 0
SCALE 2:1



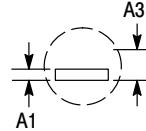
SOLDERING FOOTPRINT



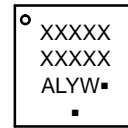
DIMENSIONS: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

onsemi, **onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi**
